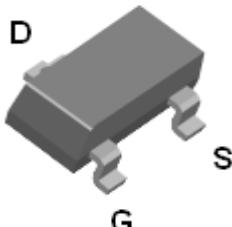


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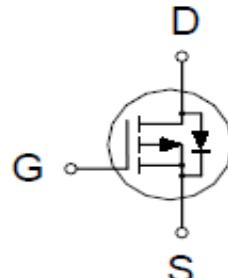
P-Channel Logic Level Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-20V	150mΩ @ $V_{GS} = -4.5V$	-3A



SOT-23



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current $T_A = 25^\circ C$	I_D	-3	A
$T_A = 70^\circ C$	I_D	-1.9	
Pulsed Drain Current ¹	I_{DM}	-12	
Avalanche Current	I_{AS}	-12	
Avalanche Energy	E_{AS}	7	mJ
Power Dissipation $T_A = 25^\circ C$	P_D	1.2	W
$T_A = 70^\circ C$	P_D	0.7	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	R_{jJA}		110	°C / W

¹Pulse width limited by maximum junction temperature.

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P-Channel Logic Level Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

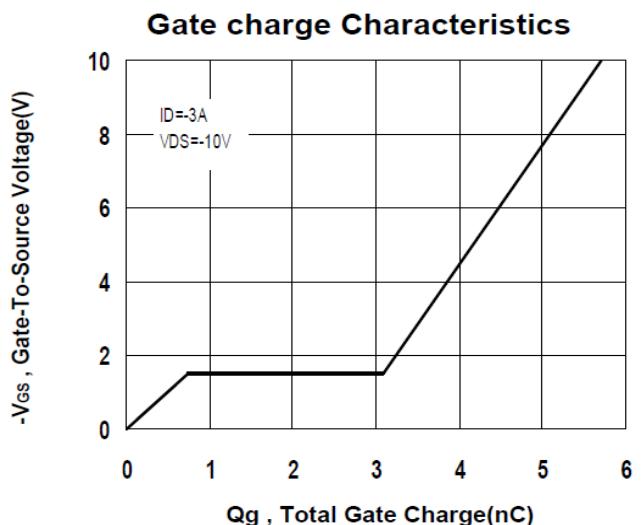
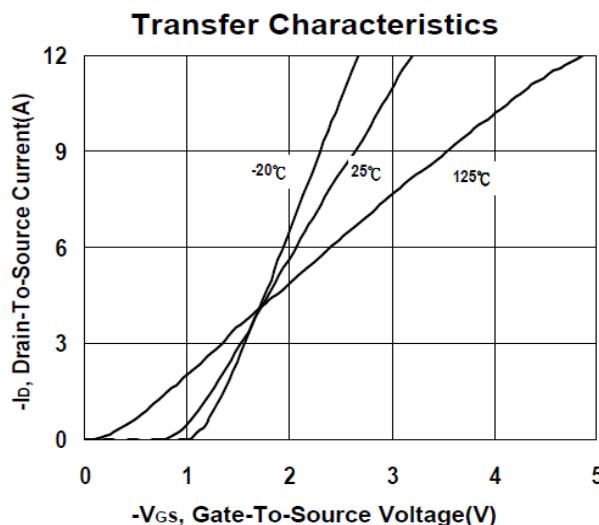
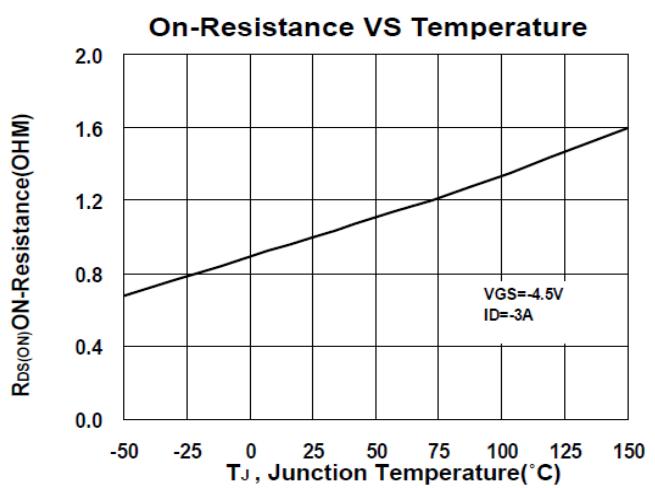
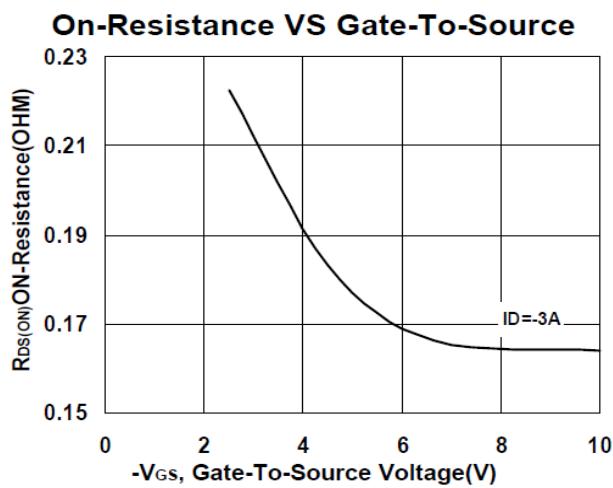
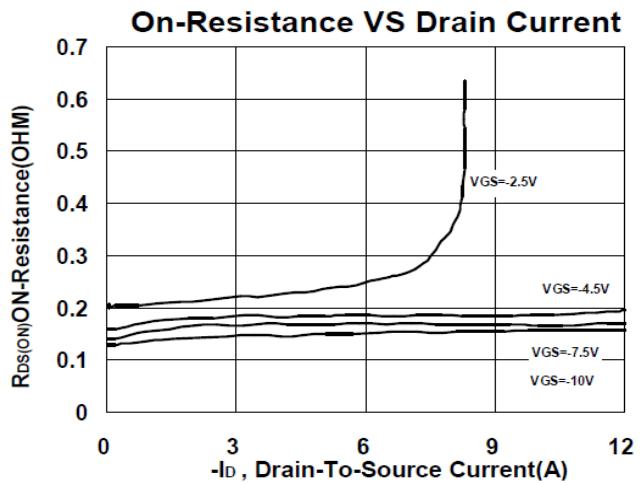
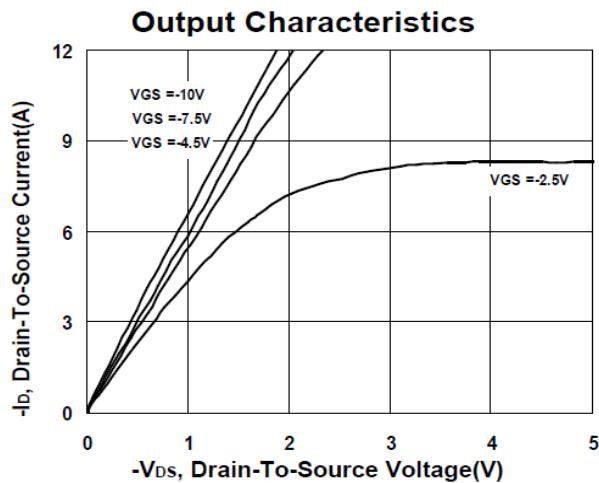
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.5	-0.9	-1.2	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 12\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -16\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
		$V_{\text{DS}} = -16\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -4.5\text{V}$	-6			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -2.5\text{V}, I_D = -1\text{A}$		118	250	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		87	150	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_D = -3\text{A}$		16		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -10\text{V}, f = 1\text{MHz}$		415		pF
Output Capacitance	C_{oss}			119		
Reverse Transfer Capacitance	C_{rss}			85		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		6.3		Ω
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 0.5V_{(\text{BR})\text{DSS}}, V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		5.8		nC
Gate-Source Charge ²	Q_{gs}			1		
Gate-Drain Charge ²	Q_{gd}			2.4		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -10\text{V}$ $I_D \approx -3\text{A}, V_{\text{GS}} = -4.5\text{V}, R_G = 6\Omega$		13		nS
Rise Time ²	t_r			36		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			42		
Fall Time ²	t_f			34		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				3	A
Forward Voltage ¹	V_{SD}	$I_F = -1\text{A}, V_{\text{GS}} = 0\text{V}$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F = -1\text{A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$		21		nS
Reverse Recovery Charge	Q_{rr}			7		nC

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

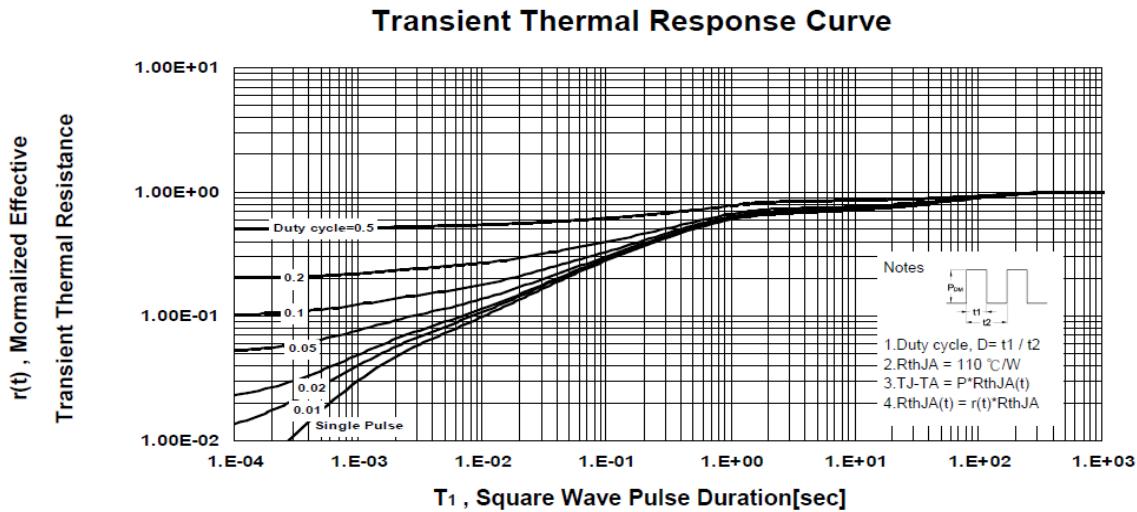
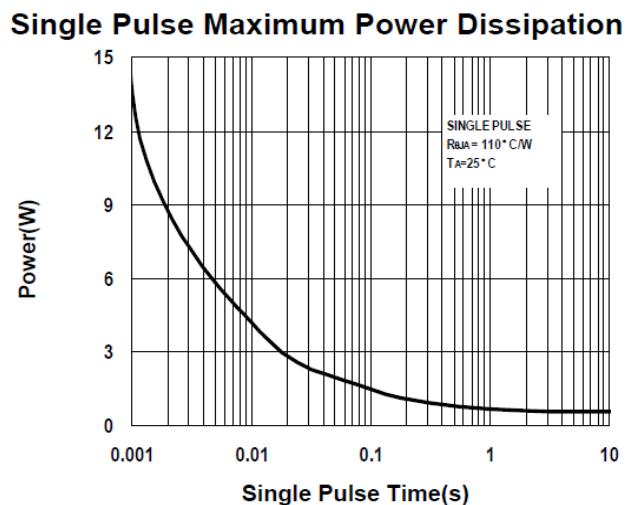
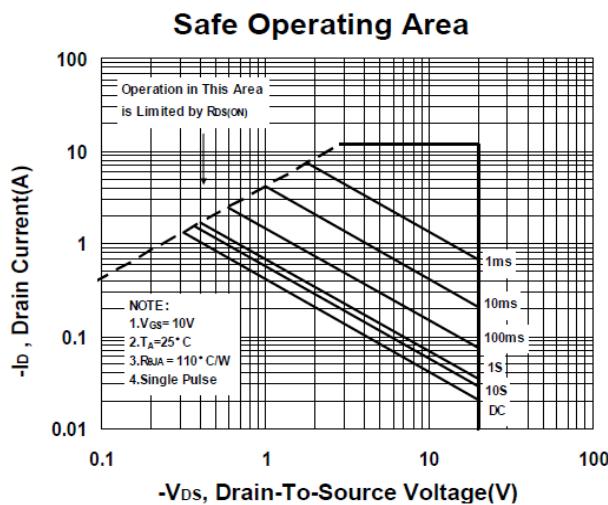
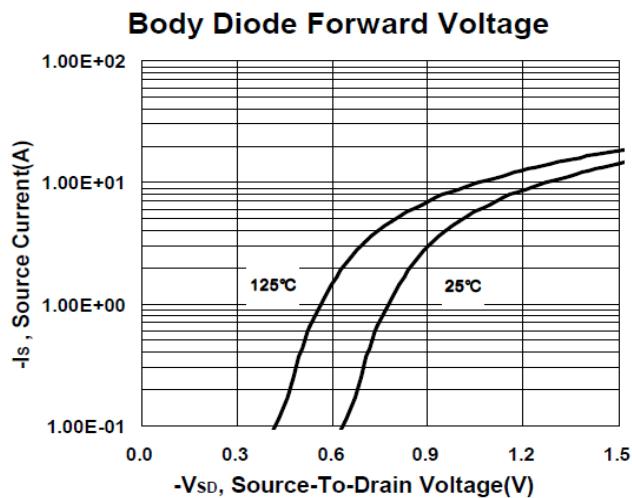
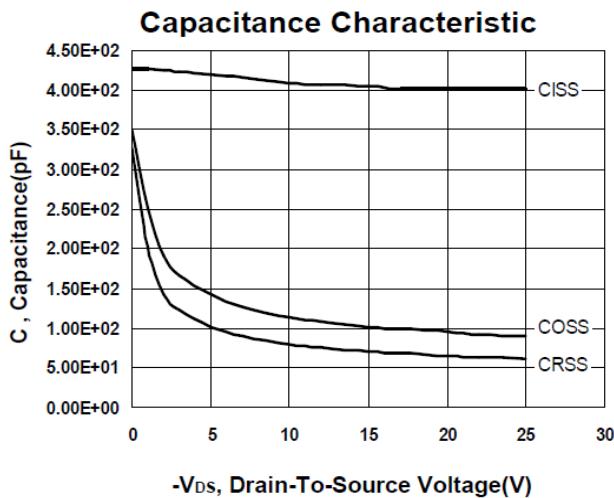
PA502FMG

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Package Dimension

SOT-23 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A		1.05		H	0.1		0.2
B	2.4		3	I	0.3		0.6
C	1.4		1.73				
D	2.7		3.1				
E	1		1.31				
F	0		0.15				
G	0.3		0.5				

